

## **AMENDMENTS TO THE SPECIFICATION:**

Please replace paragraph No. 0006 ( on page 2), with the following rewritten paragraph:

1   **[0006]**       The chip according to an ~~and~~ embodiment of the invention is of  
2   particularly simple construction that makes possible a cost-effective production  
3   process, consisting of only a few process steps, which is of particular importance  
4   when mass products, such as smart labels, are to be manufactured. The cover  
5   plate fulfils a dual function in this case. It allows the encapsulation of the chip  
6   and, at the same time, the establishment of electrical contact between the chip  
7   and the conductive layer that may consist, for example, of a transponder aerial.  
8   The chip is also mechanically stress-relieved in that the conductive layer is at  
9   least as high as the chip, or higher than the chip. This fact is particularly useful  
10  when the chip is integrated in a smart label.